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YAMASHITA(10) **Pub. No.: US 2022/0353984 A1**(43) **Pub. Date: Nov. 3, 2022**(54) **WIRING MODULE AND IMAGING APPARATUS**(71) Applicant: **SONY SEMICONDUCTOR SOLUTIONS CORPORATION,**
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CPC **H05K 1/0206** (2013.01)(57) **ABSTRACT**

A wiring module according to an embodiment of the present technology includes: a wiring board and a heat dissipation member. The wiring board includes a body portion and one or more heat dissipation vias, the body portion including a front surface layer to which a device package is connected and a rear surface layer opposite to the front surface layer, the one or more heat dissipation vias penetrating the body portion from the front surface layer to the rear surface layer. The heat dissipation member is connected to the rear surface layer so as to thermally bond with the one or more heat dissipation vias.

